

CY25CAJ-8F

Nch IGBT for Strobe Flash

REJ03G1202-0200

Preliminary

Rev.2.00

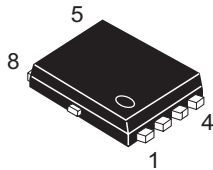
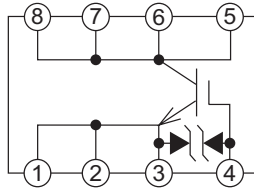
May 24, 2005

Features

- Ultra small surface mount package (VSON-8)
- V_{CES} : 400 V
- I_{CM} : 150 A
- Drive voltage: 4 V

Outline

PVSN0008JA-A
(Package Name: VSON-8<TNP-8DBV>)

1, 2 : Emitter
3 : Emitter
(for the gate drive)
4 : Gate
5, 6, 7, 8 : Collector

Note: PIN 3 is for the Gate drive only.
Note that current from the main circuit cannot flow into this section. (Please see page 3)

Applications

Strobe flash for cameras

Maximum Ratings

($T_c = 25^\circ\text{C}$)

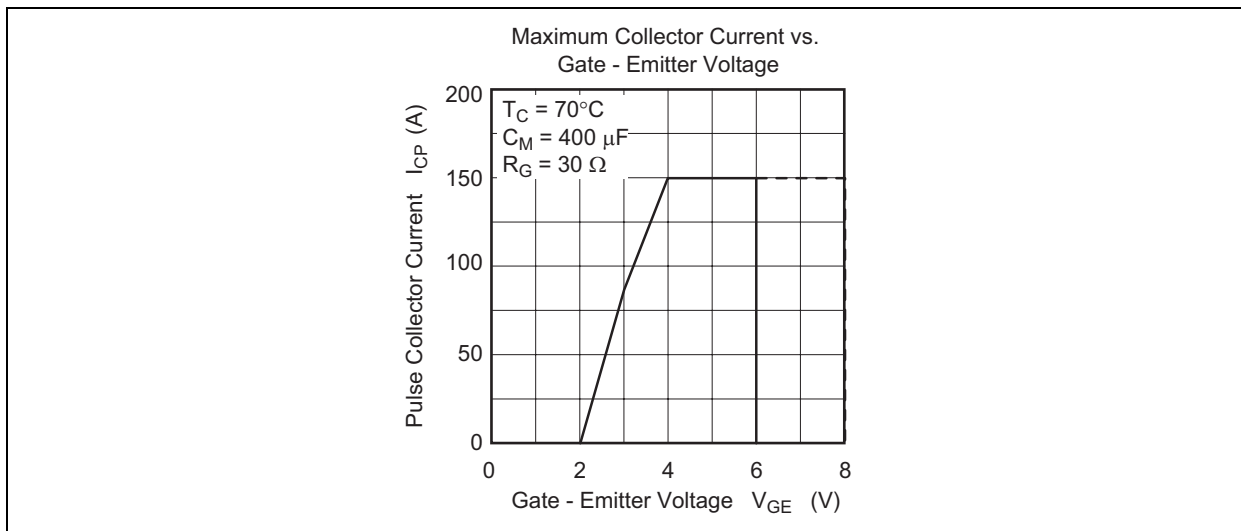
Parameter	Symbol	Ratings	Unit	Conditions
Collector-emitter voltage	V_{CES}	400	V	$V_{GE} = 0 \text{ V}$
Gate-emitter voltage	V_{GES}	± 6	V	$V_{CE} = 0 \text{ V}$
Peak gate-emitter voltage	V_{GEM}	± 8	V	$V_{CE} = 0 \text{ V}$, $t_w = 10 \text{ s}$
Collector current (Pulse)	I_{CM}	150	A	$C_M = 400 \mu\text{F}$ (see performance curve)
Junction temperature	T_j	- 40 to +150	$^\circ\text{C}$	
Storage temperature	T_{stg}	- 40 to +150	$^\circ\text{C}$	

Electrical Characteristics

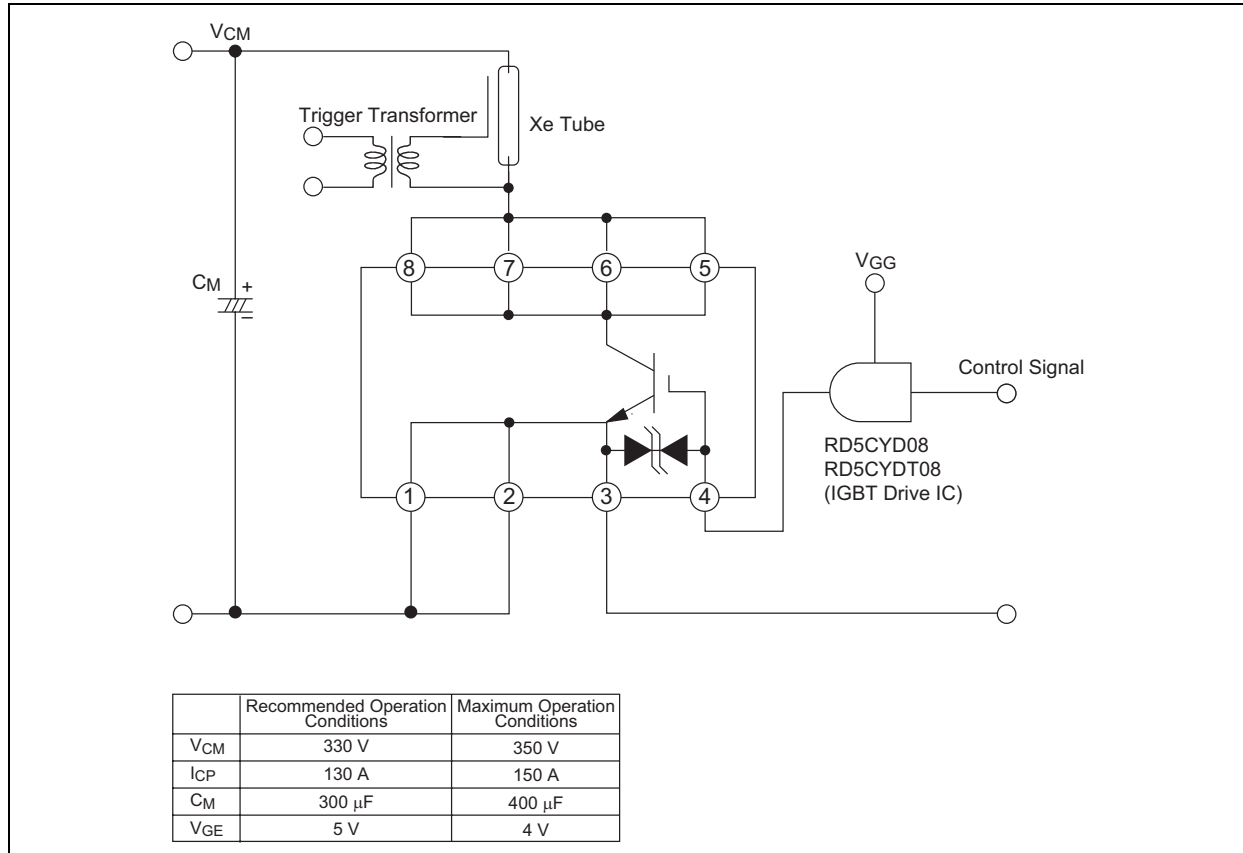
(T_j = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Collector-emitter breakdown voltage	V _{(BR)CES}	450	—	—	V	I _C = 1 mA, V _{GE} = 0 V
Collector-emitter leakage current	I _{CES}	—	—	10	μA	V _{CE} = 400 V, V _{GE} = 0 V
Gate-emitter leakage current	I _{GES}	—	—	±10	μA	V _{GE} = ±8 V, V _{CS} = 0 V
Gate-emitter threshold voltage	V _{GE(th)}	0.5	0.7	1.5	V	V _{CE} = 10 V, I _C = 1 mA
Collector-Emitter saturation voltage	V _{CE(sat)}	—	4.0	6.0	V	I _C = 150 A, V _{GE} = 4 V
Input capacitance	C _{ies}	—	3400	—	pF	V _{CE} = 25 V, V _{GE} = 10 V, f = 1MHz

Performance Curves



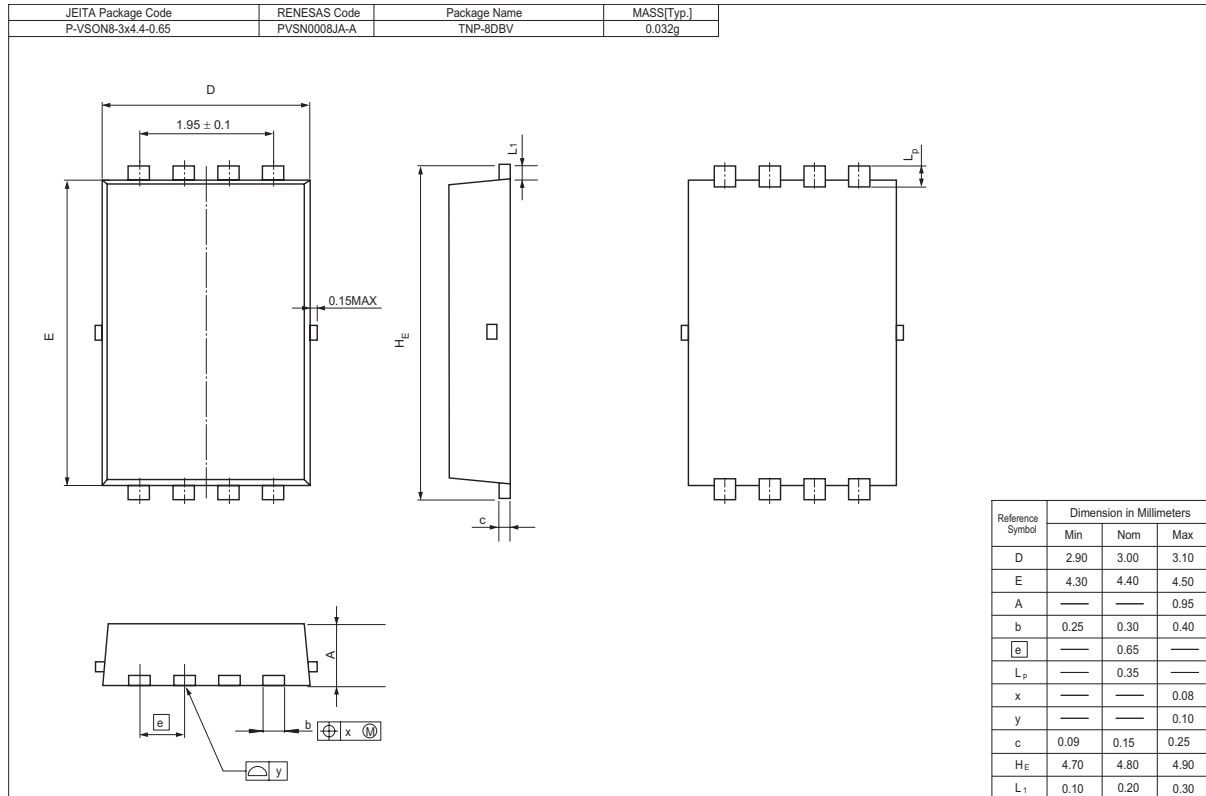
Application Example



Precautions on Usage

1. IGBT has MOS structure and its gate is insulated by thin silicon oxide. So please handle carefully to protect the device from electrostatic charge.
2. Gate drive voltage during on-period must be applied to satisfy the rating of maximum pulse collector current. And turn-off dv/dt must become less than 400 V/ μ s. In general, when $R_{G(off)} = 30 \Omega$, it is satisfied.
3. The ground of the drive signal must be connected to pin 3 only. If the emitter terminal pins 1 and 2 in which a large currents flow are given to the device as the drive signal emitter, the device may be damaged due to large currents since the specified gate voltage is not applied to the IGBT within the device.
4. The operation life should be endured until repeated discharge of 5,000 times under the charge current ($I_{Xe} \leq 150$ A : full luminescence condition) of main capacitor. ($C_M = 400 \mu$ F) Repetition period under full luminescence condition is over 3 seconds.
5. Total operation hours applied to the gate-emitter voltage must be within 5,000 hours when V_{GE} is driven at 6 V.

Package Dimensions



Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Surface-mounted type	Taping	3000	Type name – T +Direction (1 or 2)+3	CY25CAJ-8F-T13

Note : Please confirm the specification about the shipping in detail.

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